

HERSCHEL/PLANCK

Authorisation To Proceed (ATP)

FROM:	SRON-Groningen – FHFPUY
TO:	TECNOLOGICA HERSCHEL/PLANCK OFFICE
DATE:	14-03-2003
REFERENCE:	YEBES/FPU/PO/2003-002, issue 1
TOTAL PAGES:	3

CENTRO NACIONAL DE INFORMACIÓN GEOGRÁFICA (the buyer) provides hereby to Tecnológica, Componentes Electrónicos, S.A. (the agent) an Authorisation to Proceed (ATP) for the procurement of the items listed in the annex below in the associated quantities.

The foreseen maximum cost for the procurement of these parts is per currency of **0 Euro, plus 0 US Dollars** (list of all total cost split by currencies as per agent quotation based on provisional prices).

The buyer commits to use these parts exclusively for the Herschel Planck programme. All parts procured under this scheme will be subject to audit by ESA.

The relationships between buyer and agent under this ATP are regulated by the Herschel/Planck P.O. Conditions Doc. Ref. FP-TLG-CO-001 Is. 4.

This ATP will be subject to examination by ESA. If the ATP is not rejected, the parts cost will be paid directly by ESA to the CPPA. This payment will prevail over and cancel any buyer's payment obligations regulated in article 4 of the P.O. Conditions.

This ATP is a binding contract between the buyer and the agent. It is up to the buyer to issue or not a formal purchase order when the part prices are confirmed by the agent. If the buyer issues a formal purchase order which will supersede this ATP/LOL, it must refer the applicability of Doc. Ref. FP-TLG-CO-001 Is. 4 and the ATP superseded. The lack of issuing of this PO does not free the buyer from its obligations toward the agent.

The buyer: CENTRO NACIONAL DE INFORMACIÓN GEOGRÁFICA

ANNEX

Delivery:	ALCATEL ESPACIO Attn.: JOSE MARÍA DÍEZ C/ Einstein 7 28760- Tres Cantos Madrid SPAIN
Contacts:	CARMEN DIEZ, diez@cay.oan.es
VAT number	

type	partnumber	description	case_value	spec	mfr	total	user	Unit Cost	Currency
ATC111	111XCB100D100TT	chip cap, single layer, 100V, +/-0.5pF, Ti/Ni/Au termination	10pF	TPR-01-009 SRONG/FPJU/PAD/2002-023	ATC/USA	80	YEBES		
ATC111	111UDA100D100TT	chip cap, single layer, 100V, +/-0.5pF, Ti/Ni/Au termination	10pF	SRONG/FPJU/PAD/2002-023	ATC/USA	20	YEBES		
ATC111	111ZCA220J100TT	chip cap, single layer, 100V, 5%, Ti/Ni/Au termination	22pF	TPR-01-009 SRONG/FPJU/PAD/2002-023	ATC/USA	35	YEBES		
ATC111	111ZHC151J100TT	chip cap, single layer, 100V, 5%, Ti/Ni/Au termination	150pF	TPR-01-009 SRONG/FPJU/PAD/2002-023	ATC/USA	35	YEBES		
1206 Type 1 A120C	300902201C3901JC	chip cap, Type I, 5%, 50V, AgPd termination	3nF9	ESA/SCC3009/022 SRONG/FPJU/PAD/2002-012	AVX-TPC/FRA	35	YEBES		
1206 Type 1 A120C	300902206C3901JC	chip cap, Type I, 5%, 50V, Ni barrier/solder	3nF9	ESA/SCC3009/022 SRONG/FPJU/PAD/2002-001	AVX-TPC/FRA	35	YEBES		
1812 Type 1 A114C	300900501C1802JC	chip cap, Type I, 5%, 50V, AgPd termination	18nF	ESA/SCC3009/005 SRONG/FPJU/PAD/2002-0?	AVX-TPC/FRA	35	YEBES		
1812 Type 1 A114C	300900506C1802JC	chip cap, Type I, 5%, 50V, Ni barrier/solder termination	18nF	ESA/SCC3009/005 SRONG/FPJU/PAD/2002-0?	AVX-TPC/FRA	35	YEBES		
	340102901B9PFR112	09P/P insulated solid wire	-	ESA/SCC3401/029	CAN/FRA	14	YEBES		
	340102901B9SFR116	09R/S uninsulated solid wire	-	ESA/SCC3401/029	CAN/FRA	14	YEBES		
322-9500-000B	340103201B	screw lock assembly	-	ESA/SCC3401/032	CAN/FRA	28	YEBES		
115366-9201	340103205B	screw lock assembly saver	-	ESA/SCC3401/032	CAN/FRA	14	YEBES		
MDM-115366-9532C-BT	340104101B9PS	MDM saver 9PS	-	ESA/SCC3401/041	CAN/FRA	14	YEBES		
SMA	340200219B201	RF coax female off-set tab	-	ESA/SCC3402/002	RAD/ALL	24	YEBES		
SMA	340200302B201	RF coax adaptor male/female	-	ESA/SCC3403/006	RAD/ALL	24	YEBES		
SMA	340300601B	RF load, fixed, coaxial, male	-	ESA/SCC3402/004	RAD/ALL	24	YEBES		
H0302 (SOA005)	H0302AP102G10G	chip res, 2%, 300ppm, Au termination	1K00	SOA005 SRONG/FPJU/PAD/2002-014	SOTA/USA	35	YEBES		
H0302 (SOA005)	H0302AP15R0G10G	chip res, 2%, 100ppm, Au termination	15R0	SOA005 SRONG/FPJU/PAD/2002-014	SOTA/USA	55	YEBES		
H0302 (SOA005)	H0302CP204G30PS	chip res, 2%, 300ppm, Pd/Ag termination	200K	SOA005 SRONG/FPJU/PAD/2002-015	SOTA/USA	35	YEBES		
H0302 (SOA005)	H0302CP221G10PS	chip res, 2%, 100ppm, Pd/Ag termination	220R	SOA005 SRONG/FPJU/PAD/2002-015	SOTA/USA	20	YEBES		
H0302 (SOA005)	H0302CP49R9F10PS	chip res, 1%, 100ppm, Pd/Ag termination	49R9	SOA005 SRONG/FPJU/PAD/2002-015	SOTA/USA	35	YEBES		

Issue: 01

type	partnumber	description	case_value	spec	mfr	total	user	Unit Cost	Currency
H0302 (SOA005)	H0302CP133G30PS	chip res, 2%, 300ppm, Pd/Ag termination	13K	SOA005 SRONG/FPU/PAD/2002-015	SOTA/USA	35	YEBES		
H0302 (SOA005)	H0302CPx204G30	chip res, 2%, 300ppm, Ni/pretinned	200K	SOA005 SRONG/FPU/PAD/2002-007	SOTA/USA	35	YEBES		
H0302 (SOA005)	H0302CPX221G10	chip res, 2%, 100ppm, Ni/pretinned	220R	SOA005 SRONG/FPU/PAD/2002-007	SOTA/USA	20	YEBES		
H0302 (SOA005)	H0302CPX49R9F10	chip res, 1%, 100ppm, Ni/pretinned	49R9	SOA005 SRONG/FPU/PAD/2002-007	SOTA/USA	35	YEBES		
H0302 (SOA005)	H0302CPX133G30	chip res, 2%, 300ppm, Ni/pretinned	13K	SOA005 SRONG/FPU/PAD/2002-007	SOTA/USA	35	YEBES		

Components need date: 01 September 2003

Total	0.00	Euro
Total	0.00	USDollar